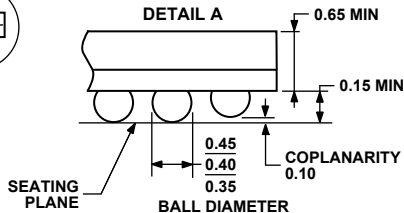
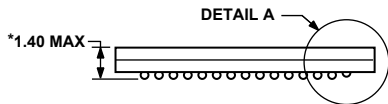
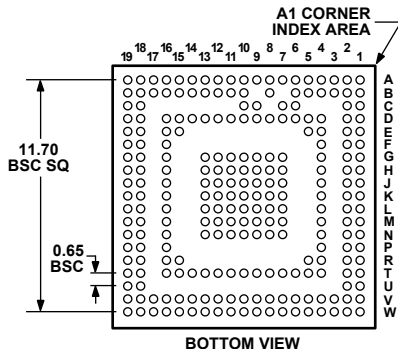
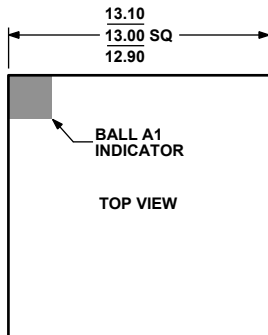


# 237-Lead Chip Scale Package Ball Grid Array [CSP\_BGA]

(BC-237-2)

Dimensions shown in millimeters

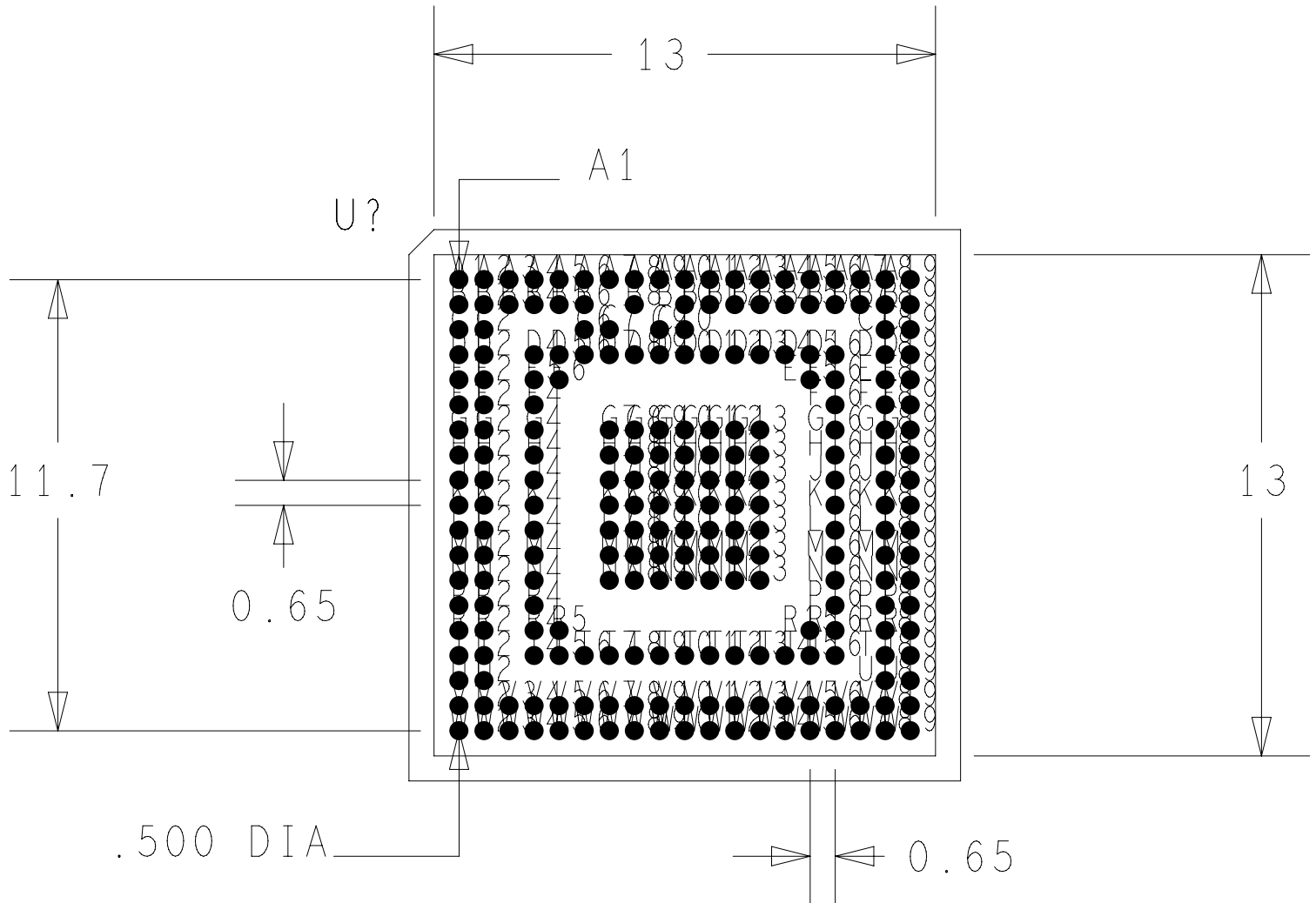


\*COMPLIANT TO JEDEC STANDARDS MO-225  
WITH THE EXCEPTION TO PACKAGE HEIGHT.

# Analog Devices

BC-237-2

REV A



( Dim. are in MM )

LAST MODIFIED 09/13/07